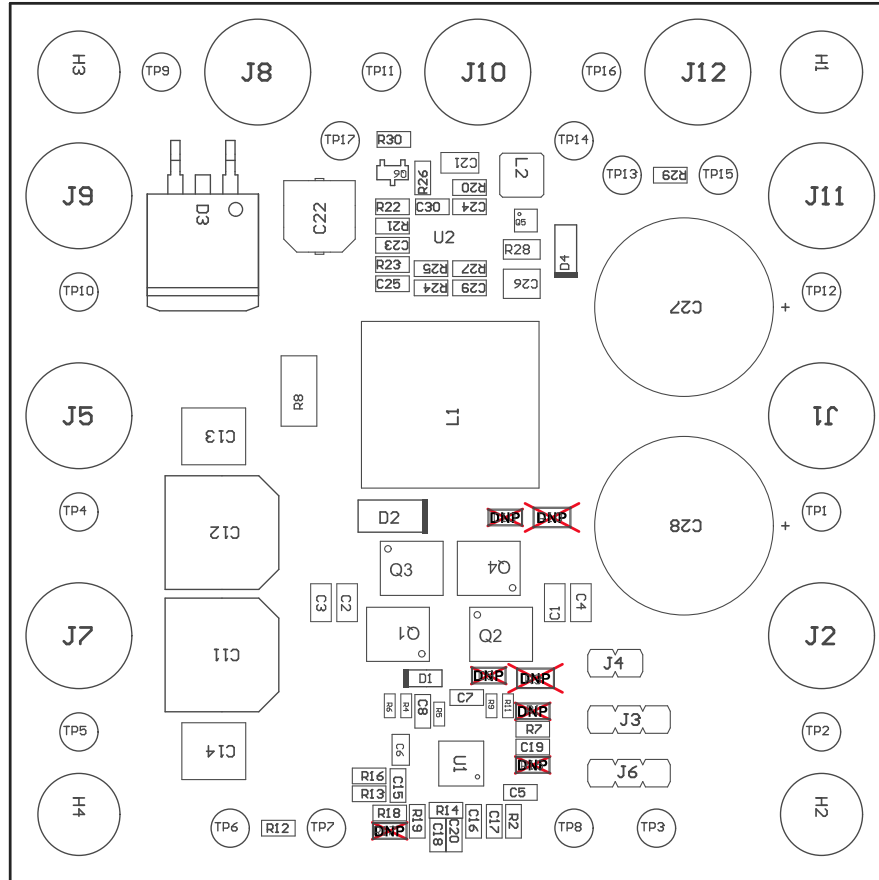


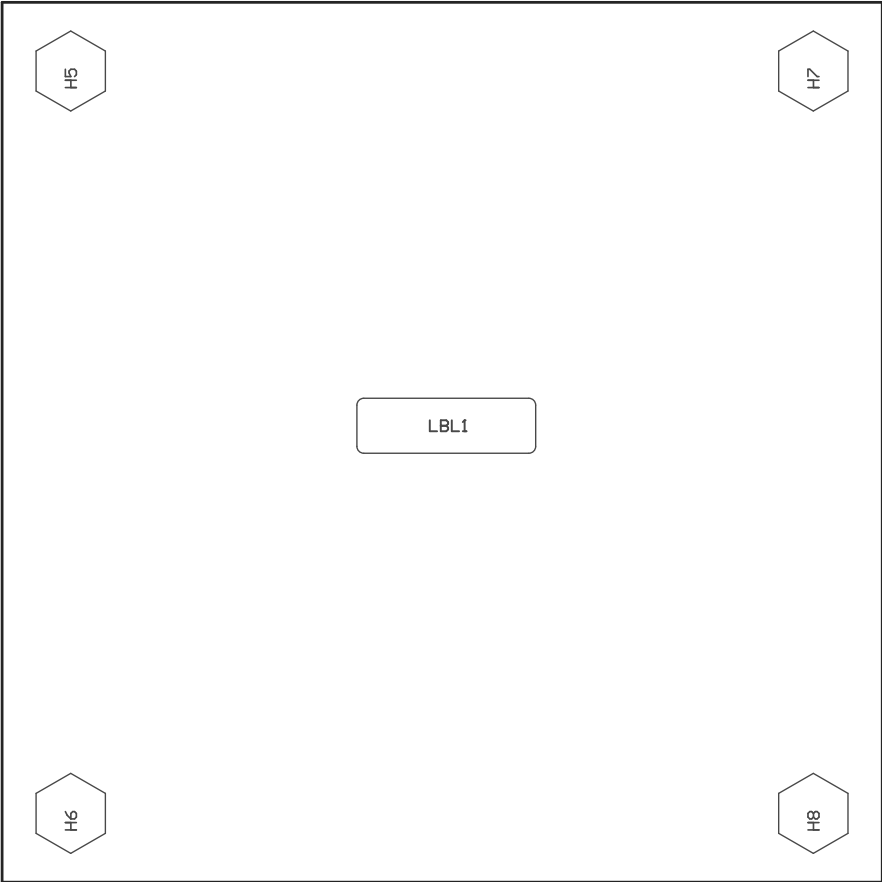
ZX1 ■ 50VIN = 13 - 50VDC
 ZX2 ■ 11VOUT = 11VDC at 13.6A
 ZX3 ■ Fsw = 440kHz
 ZX4 ■ 12VIN = 12VDC
 ZX5 ■ 50VOUT = 50VDC @ 10mA
 ZX6 ■ Fsw = 250kHz

- ZZ1 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
 ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
 ZZ3 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
 ZZ4 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
 ZZ5 ■ Install Shunt Jumper SH-J1 onto J4
 ZZ6 ■ Install Shunt Jumper SH-J3 onto J3 pin 2-3.
 ZZ7 ■ Install Shunt Jumper SH-J4 onto J6 pins 1-2.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP20818	REV: A	SVN REV: Not In VersionControl
	TID #: PMP20818		
PLOT NAME = Top Assembly Drawing	GENERATED : 3/29/2017 12:08:57 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP20818	REV: A	SVN REV: Not In VersionControl
	TID #: PMP20818		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 3/29/2017 12:08:58 PM		TEXAS INSTRUMENTS

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